/ Descriptions

TO-263

Schottky Diode in a TO-263F Plastic Package.

/ Features

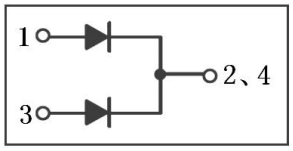
Low forward voltage drop,low power losses,High efficiency operation.

/ Applications

OR-ing DC-DC

For use in high frequency inverters, switching power supplies, freewheeling diodes, OR-ing diode, dc-to-dc converters and reverse battery protection.

/ Equivalent Circuit



/ Pinning



PIN1 Anode PIN 2 4 Cathode PIN 3 Anode

/ h_{FE} Classifications & Marking

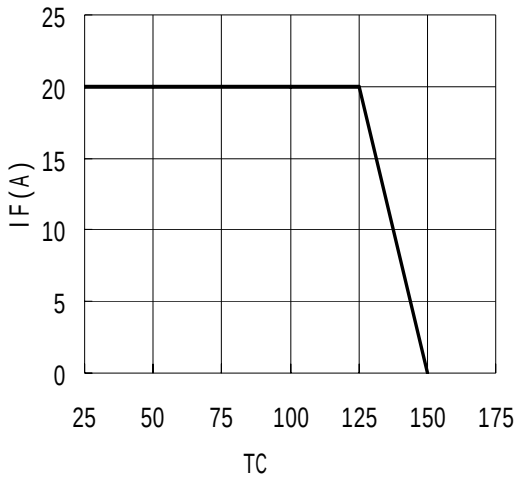
See Marking Instructions.

Parameter	Symbol	Rating	Unit
Recurrent Peak Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RM} V_{RSM} V_{DC}	150	V
RMS Voltage	V_{RMS}	105	V
Average Rectified Forward Current	$I_{F(AV)}$	2 × 10	A
Non Repetitive Peak Surge Current	I_{FSM}	120	A
Thermal Resistance Junction to Case	R_{Jc}	5.0	/W
Junction and Storage Temperature Range	T_j T_{stg}	-55 +150	

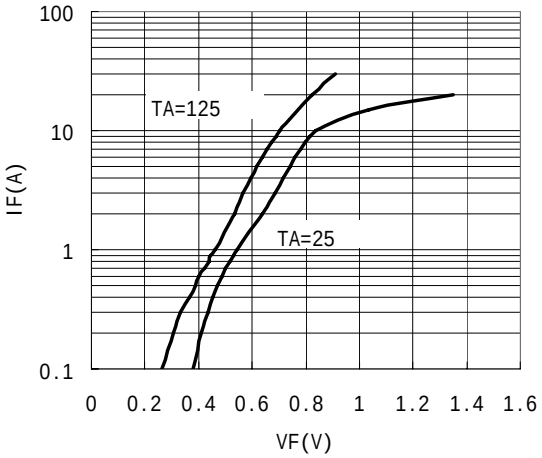
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Breakdown Voltage	V_{BR}	I_R=1mA(Ta=25)	150			V
		I_F =5A(Ta=25)		0.74		V
Forward Voltage	V_F	I_F =10A(T				

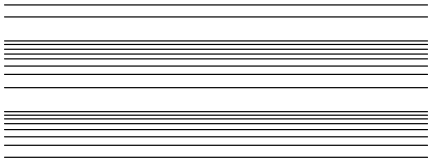
/ Electrical Characteristic Curve

IF - TC

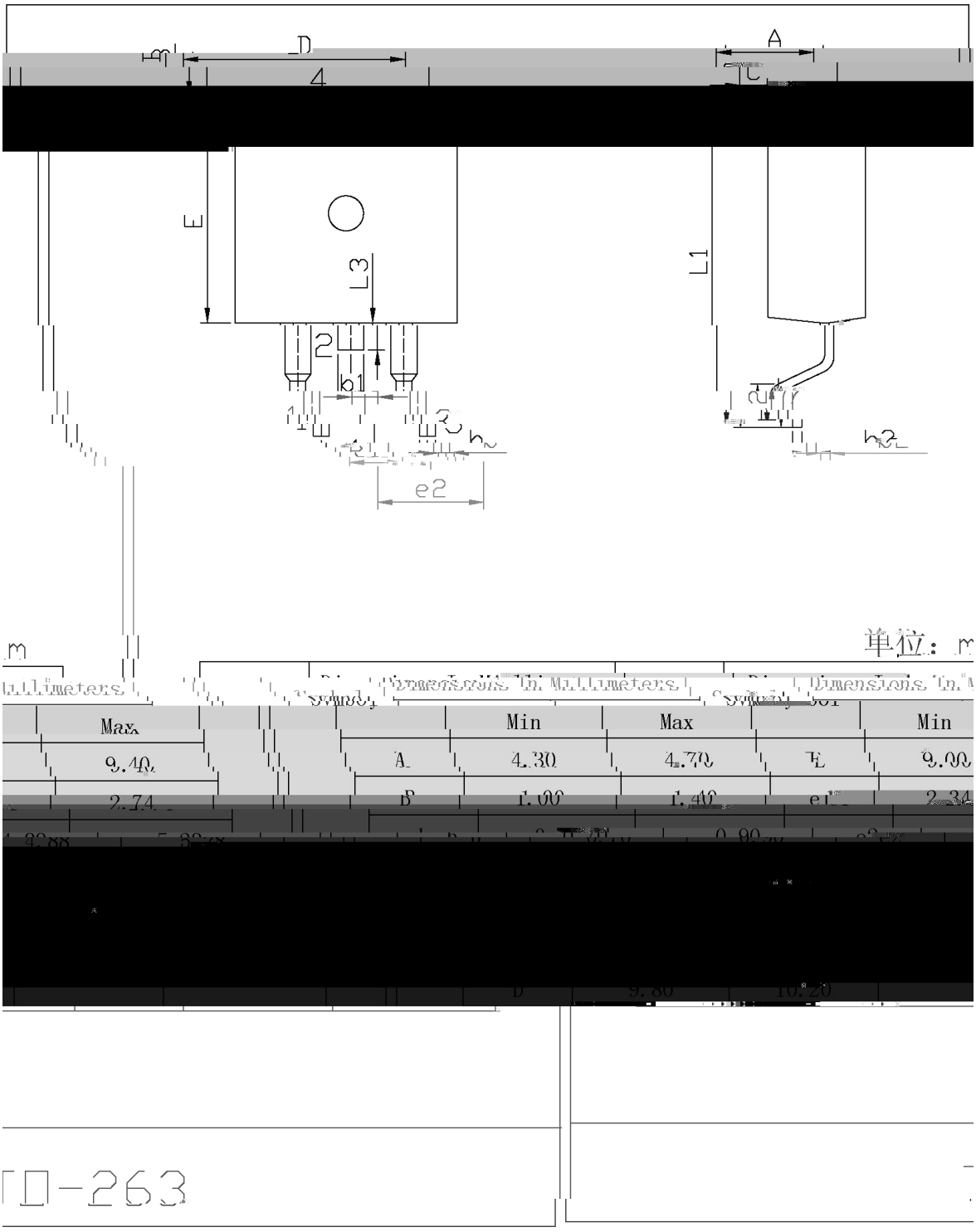


IF - VF

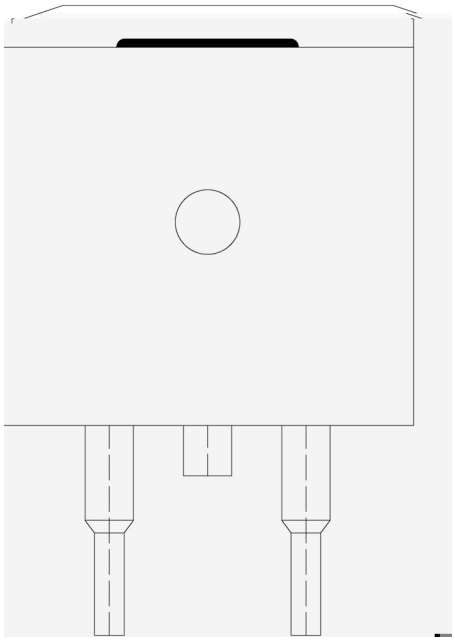




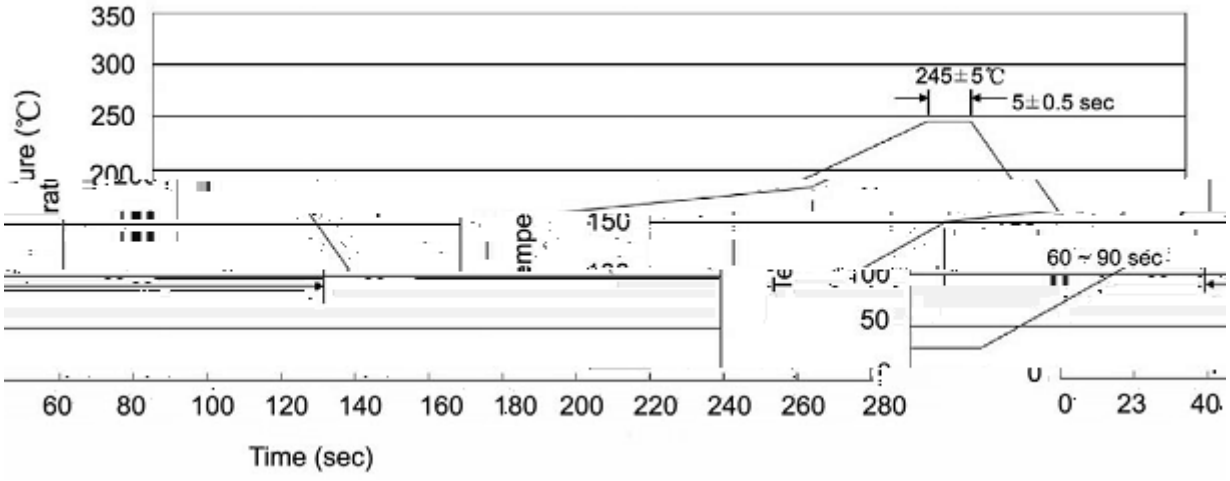
/ Package Dimensions



/ Marking Instructions



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



		Note:	
1	25 150 60 90sec;	1.Preheating:25~150 , Time:60~90sec.	
2	245±5 5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.	
3	2 10 /sec.	3. Cooling Speed: 2~10 /sec.	

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit mm³)
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
TO-263	800	1	800	5	4,000	13 ×24	360×360×50	385×257×392

/ TUBE

Package Type	Units			Dimension	(unit mm³)
	Units/Tube /	Tubes/Inner Box /	Units/Inner Box		